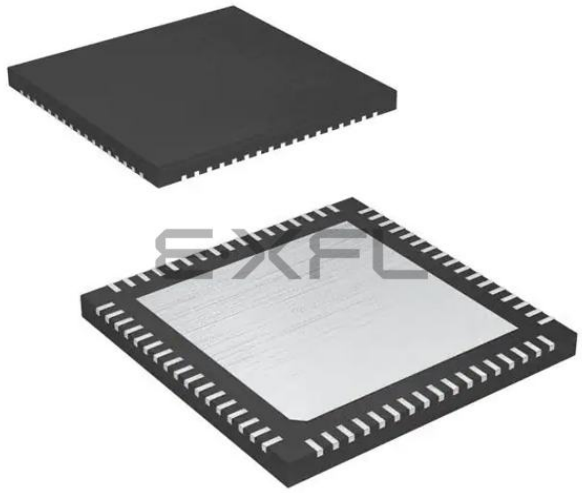
Analog Devices Inc./Maxim Integrated - 73S1217F-68IMR/F Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80515
Core Size	8-Bit
Speed	24MHz
Connectivity	I²C, SmartCard, UART/USART, USB
Peripherals	LED, POR, WDT
Number of I/O	8
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 6.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	68-VFQFN Exposed Pad
Supplier Device Package	68-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/73s1217f-68imr-f

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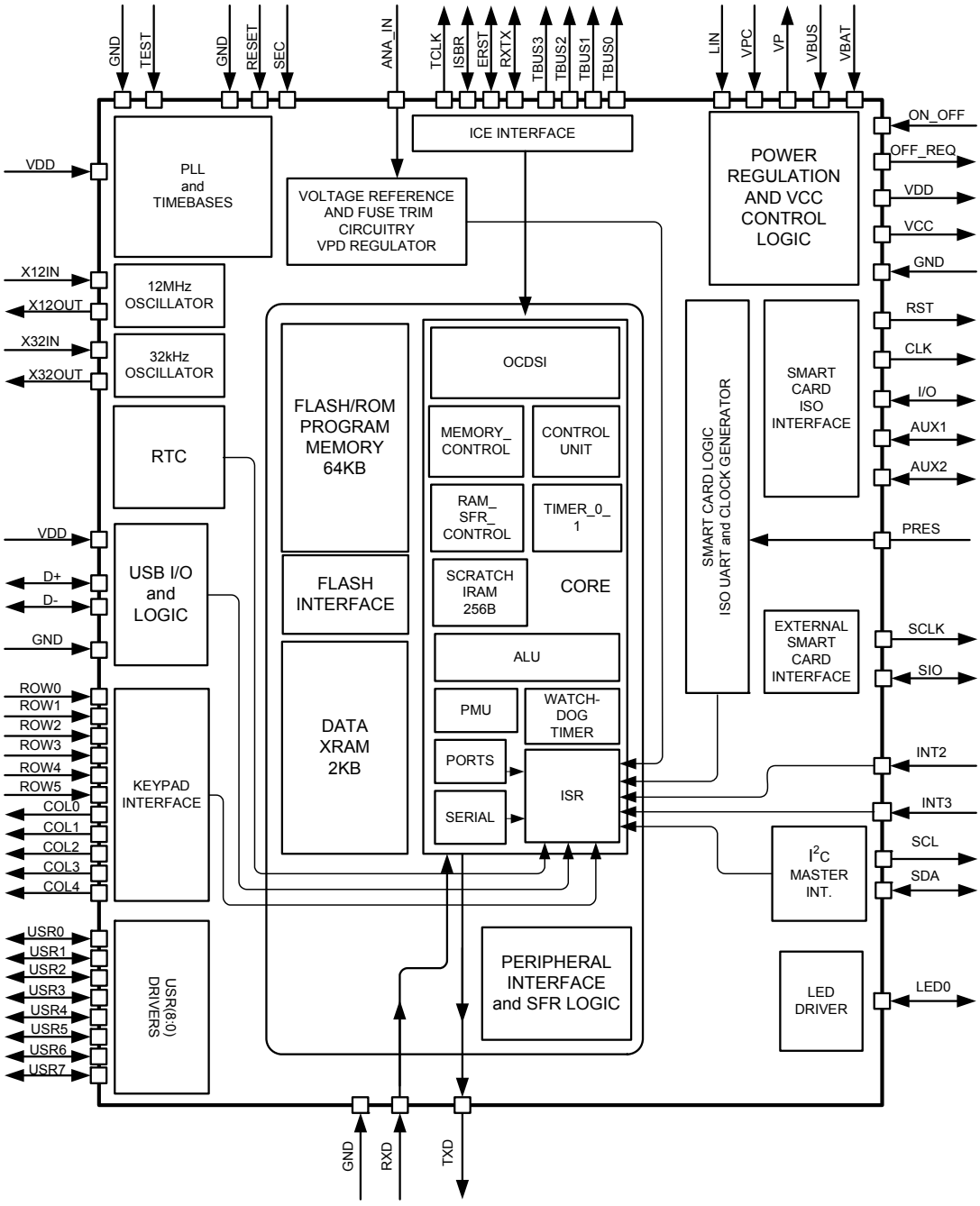

Figure 1: IC Functional Block Diagram

Program Memory: The 80515 can address up to 64KB of program memory space from 0x0000 to 0xFFFF. Program memory is read when the MPU fetches instructions or performs a MOVC operation. After reset, the MPU starts program execution from location 0x0000. The lower part of the program memory includes reset and interrupt vectors. The interrupt vectors are spaced at 8-byte intervals, starting from 0x0003. Reset is located at 0x0000.

Flash Memory: The program memory consists of flash memory. The flash memory is intended to primarily contain MPU program code. Flash erasure is initiated by writing a specific data pattern to specific SFR registers in the proper sequence. These special pattern/sequence requirements prevent inadvertent erasure of the flash memory.

The mass erase sequence is:

1. Write 1 to the FLSH_MEEN bit in the FLSHCTL register (SFR address 0xB2[1]).
2. Write pattern 0xAA to ERASE (SFR address 0x94)

Note: The mass erase cycle can only be initiated when the ICE port is enabled.

The page erase sequence is:

1. Write the page address to PGADDR (SFR address 0xB7[7:1])
2. Write pattern 0x55 to ERASE (SFR address 0x94)

The PGADDR register denotes the page address for page erase. The page size is 512 (200h) bytes and there are 128 pages within the flash memory. The PGADDR denotes the upper seven bits of the flash memory address such that bit 7:1 of the PGADDR corresponds to bit 15:9 of the flash memory address. Bit 0 of the PGADDR is not used and is ignored. The MPU may write to the flash memory. This is one of the non-volatile storage options available to the user. The FLSHCTL SFR bit FLSH_PWE (flash program write enable) differentiates 80515 data store instructions (MOVX@DPTR,A) between Flash and XRAM writes. Before setting FLSH_PWE, all interrupts need to be disabled by setting EAL = 1. Table 3 shows the location and description of the 73S1217F flash-specific SFRs.

Any flash modifications must set the CPUCLK to operate at 3.6923 MHz (MPUCLKCtl = 0x0C) before any flash memory operations are executed to insure the proper timing when modifying the flash memory.

1.5 Special Function Registers (SFRs)

The 1217 utilizes numerous SFRs to communicate with the many 1217 peripherals. This results in the need for more SFR locations outside the direct address IRAM space (0x80 to 0xFF). While some peripherals are mapped to unused IRAM SFR locations, additional SFRs for the USB, smart card and other peripheral functions are mapped to the top of the XRAM data space (0xFC00 to 0xFFFF).

1.5.1 Internal Data Special Function Registers (SFRs)

The Special Function Registers map is shown in Table 6.

Table 6: IRAM Special Function Registers Locations

Hex\Bin	X000	X001	X010	X011	X100	X101	X110	X111	Bin/ Hex
F8									FF
F0	B								F7
E8									EF
E0	A								E7
D8	BRCON								DF
D0	PSW	**KCOL**	**KROW**	**KSCAN**	**KSTAT**	**KSIZE**	**KORDERL**	**KORDERH**	D7
C8	T2CON								CF
C0	IRCON								C7
B8	IEN1	IP1	S0RELH	S1RELH					BF
B0			**FLSHCTL**					**PGADDR**	B7
A8	IEN0	IP0	S0RELL						AF
A0									A7
98	S0CON	S0BUF	IEN2	S1CON	S1BUF	S1RELL			9F
90	**USR70**	**UDIR70**	DPS		**ERASE**				97
88	TCON	TMOD	TL0	TL1	TH0	TH1		**MCLKCtl**	8F
80		SP	DPL	DPH	DPL1	DPH1	WDTREL	PCON	87

Only a few addresses are used, the others are not implemented. SFRs specific to the 73S1217F are shown in **bold** print (gray background). Any read access to unimplemented addresses will return undefined data, while most write access will have no effect. However, a few locations are reserved and not user configurable in the 73S1217F. **Writes to the unused SFR locations can affect the operation of the core and therefore must not be written to. This applies to all the SFR areas in both the IRAM and XRAM spaces. In addition, all unused bit locations within valid SFR registers must be left in their default (power on default) states.**

1.7.2 Power Supply Management

The detailed power supply management logic block diagram is shown in Figure 5.

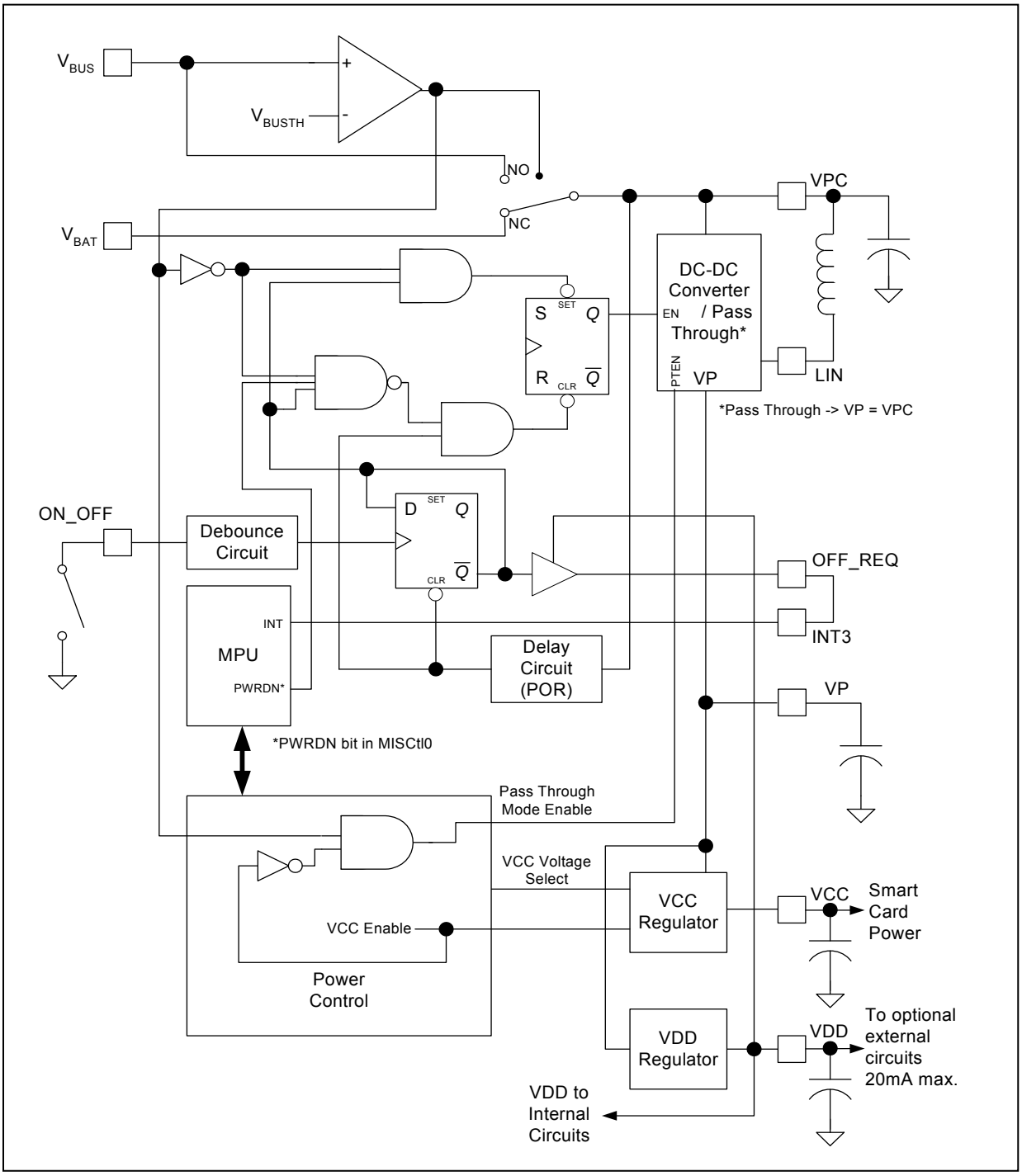

Figure 5: Detailed Power Management Logic Block Diagram

The 73S1217F contains a power supply and converter circuit that takes power from any one of three sources; V_{PC}, V_{BUS}, or V_{BAT}.

V_{PC} is specified to range from 2.7 to 6.5 volts. It can typically be supplied by a single cell battery with a voltage range of 2.7 to approximately 3.1 volts or by a standard supply of 3.3 or 5 volts.

Interrupt Priority 1 Register (IP1): 0xB9 ← 0x00

Table 29: The IP1 Register

MSB							LSB
–	–	IP1.5	IP1.4	IP1.3	IP1.2	IP1.1	IP1.0

Table 30: Priority Levels

IP1.x	IP0.x	Priority Level
0	0	Level0 (lowest)
0	1	Level1
1	0	Level2
1	1	Level3 (highest)

Table 31: Interrupt Polling Sequence

External interrupt 0	Polling sequence ↓
Serial channel 1 interrupt	
Timer 0 interrupt	
External interrupt 2	
External interrupt 1	
External interrupt 3	
Timer 1 interrupt	
Serial channel 0 interrupt	
External interrupt 4	
External interrupt 5	
External interrupt 6	

1.7.5.6 Interrupt Sources and Vectors

Table 32 shows the interrupts with their associated flags and vector addresses.

Table 32: Interrupt Vectors

Interrupt Request Flag	Description	Interrupt Vector Address
N/A	Chip Reset	0x0000
IE0	External interrupt 0	0x0003
TF0	Timer 0 interrupt	0x000B
IE1	External interrupt 1	0x0013
TF1	Timer 1 interrupt	0x001B
RI0/TI0	Serial channel 0 interrupt	0x0023
RI1/TI1	Serial channel 1 interrupt	0x0083
IEX2	External interrupt 2	0x004B
IEX3	External interrupt 3	0x0053
IEX4	External interrupt 4	0x005B
IEX5	External interrupt 5	0x0063
IEX6	External interrupt 6	0x006B

Transmit and receive data are transferred via this register.

Table 38: The S0CON Register

MSB							LSB
SM0	SM1	SM20	REN0	TB80	RB80	TI0	RI0

Bit	Symbol	Function
S0CON.7	SM0	These two bits set the UART0 mode:
S0CON.6	SM1	
S0CON.5	SM20	Enables the inter-processor communication feature.
S0CON.4	REN0	If set, enables serial reception. Cleared by software to disable reception.
S0CON.3	TB80	The 9th transmitted data bit in Modes 2 and 3. Set or cleared by the MPU, depending on the function it performs (parity check, multiprocessor communication etc.).
S0CON.2	RB80	In Modes 2 and 3 it is the 9th data bit received. In Mode 1, if SM20 is 0, RB80 is the stop bit. In Mode 0 this bit is not used. Must be cleared by software.
S0CON.1	TI0	Transmit interrupt flag, set by hardware after completion of a serial transfer. Must be cleared by software.
S0CON.0	RI0	Receive interrupt flag, set by hardware after completion of a serial reception. Must be cleared by software.

Mode	Description	SM0	SM1
0	N/A	0	0
1	8-bit UART	0	1
2	9-bit UART	1	0
3	9-bit UART	1	1

1.7.6.2 Serial Interface 1

The Serial Interface 1 can operate in 2 modes:

- **Mode A**

  This mode is similar to Mode 2 and 3 of Serial interface 0, 11 bits are transmitted or received: a start bit (0), 8 data bits (LSB first), a programmable 9th bit, and a stop bit (1). The 9th bit can be used to control the parity of the serial interface: at transmission, bit TB81 in S1CON is outputted as the 9th bit, and at receive, the 9th bit affects RB81 in Special Function Register S1CON. The only difference between Mode 3 and A is that in Mode A only the internal baud rate generator can be use to specify baud rate.

- **Mode B**

  This mode is similar to Mode 1 of Serial interface 0. Pin RX serves as input, and TX serves as serial output. No external shift clock is used, 10 bits are transmitted: a start bit (always 0), 8 data bits (LSB first), and a stop bit (always 1). On receive, a start bit synchronizes the transmission, 8 data bits are available by reading S1BUF, and stop bit sets the flag RB81 in the Special Function Register S1CON. In mode 1, the internal baud rate generator is use to specify the baud rate.

The S1BUF register is used to read/write data to/from the serial 1 interface.

External Interrupt Control Register (USRIntCtl1) : 0xFF90 ← 0x00

Table 50: The USRIntCtl1 Register

MSB							LSB
–	U1IS.6	U1IS.5	U1IS.4	–	U0IS.2	U0IS.1	U0IS.0

External Interrupt Control Register (USRIntCtl2) : 0xFF91 ← 0x00

Table 51: The USRIntCtl2 Register

MSB							LSB
–	U3IS.6	U3IS.5	U3IS.4	–	U2IS.2	U2IS.1	U2IS.0

External Interrupt Control Register (USRIntCtl3) : 0xFF92 ← 0x00

Table 52: The USRIntCtl3 Register

MSB							LSB
–	U5IS.6	U5IS.5	U5IS.4	–	U4IS.2	U4IS.1	U4IS.0

External Interrupt Control Register (USRIntCtl4) : 0xFF93 ← 0x00

Table 53: The USRIntCtl4 Register

MSB							LSB
–	U7IS.6	U7IS.5	U7IS.4	–	U6IS.2	U6IS.1	U6IS.0

External Interrupt Control Register (INT6Ctl): 0xFF95 ← 0x00

Table 60: The INT6Ctl Register

MSB LSB

–	–	VFTIEN	VFTINT	I2CIEN	I2CINT	ANIEN	ANINT

Bit	Symbol	Function
INT6Ctl.7	–	
INT6Ctl.6	–	
INT6Ctl.5	VFTIEN	VDD fault interrupt enable.
INT6Ctl.4	VFTINT	VDD fault interrupt flag.
INT6Ctl.3	I2CIEN	I^2C interrupt enabled.
INT6Ctl.2	I2CINT	I^2C interrupt flag.
INT6Ctl.1	ANIEN	If ANIEN = 1 Analog Compare event interrupt is enabled. When masked (ANIEN = 0), ANINT (bit 0) may be set, but no interrupt is generated.
INT6Ctl.0	ANINT	(Read Only) Set when the selected ANA_IN signal changes with respect to the selected threshold if Compare_Enable is asserted. Cleared on read of register.

1.7.14 Keypad Interface

The 73S1217F supports a 30-button (6 row x 5 column) keypad (SPST Mechanical Contact Switches) interface using 11 dedicated I/O pins. Figure 13 shows a simplified block diagram of the keypad interface.

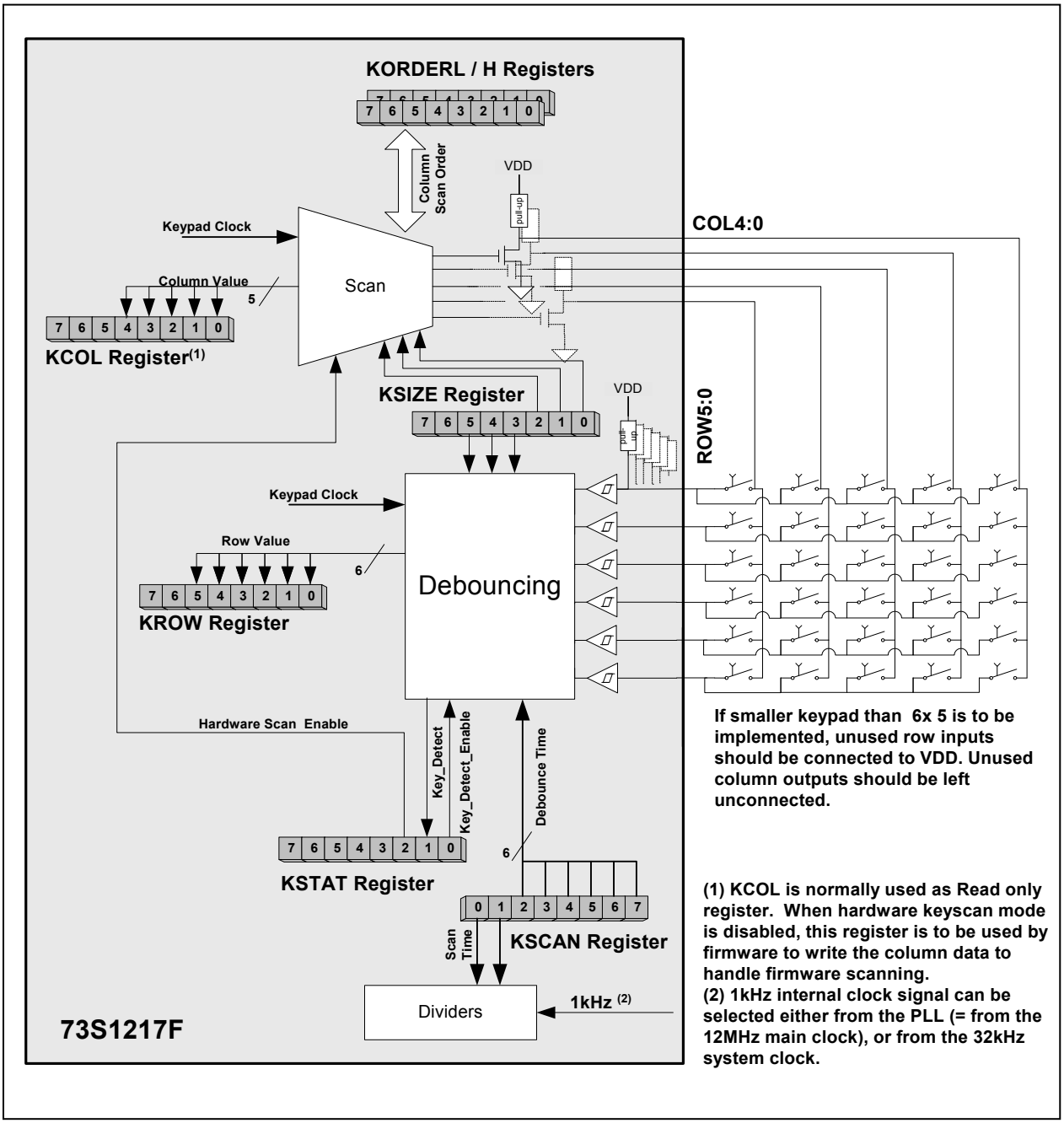

Figure 13: Simplified Keypad Block Diagram

There are five drive lines (outputs) corresponding to columns and six sense lines (inputs) corresponding to rows. Hysteresis and pull-ups are provided on all inputs (rows), which eliminate the need for external resistors in the keypad. Key scanning happens by asserting one of the 5 column lines low and looking for a low on a sense line indicating that a key is pressed (switch closed) at the intersection of the drive/sense (column/row) line in the keypad. Key detection is performed by hardware with an incorporated debounce timer. Debouncing time is adjustable through the KSCAN register. Internal hardware circuitry performs

SRX Control/Status Register (SRXCtl): 0xFE08 ← 0x00

This register is used to monitor reception of data from the smart card.

Table 87: The SRXCtl Register

MSB LSB

BIT9DAT	–	LASTRX	CRCERR	RXFULL	RXEMTY	RXOVRR	PARITYE

Bit	Symbol	Function
SRXCtl.7	BIT9DAT	Bit 9 Data – When in sync mode and with MODE9/8B set, this bit will contain the data on IO (or SIO) pin that was sampled on the ninth CLK (or SCLK) rising edge. This is used to read data in synchronous 9-bit formats.
SRXCtl.6	–	
SRXCtl.5	LASTRX	Last RX Byte – User sets this bit during the reception of the last byte. When byte is received and this bit is set, logic checks CRC to match 0x1D0F (T=1 mode) or LRC to match 00h (T=1 mode), otherwise a CRC or LRC error is asserted.
SRXCtl.4	CRCERR	(Read only) 1 = CRC (or LRC) error has been detected.
SRXCtl.3	RXFULL	(Read only) RX FIFO is full. Status bit to indicate RX FIFO is full.
SRXCtl.2	RXEMTY	(Read only) RX FIFO is empty. This is only a status bit and does not generate an RX interrupt.
SRXCtl.1	RXOVRR	RX Overrun – (Read Only) Asserted when a receive-over-run condition has occurred. An over-run is defined as a byte was received from the smart card when the RX FIFO was full. Invalid data may be in the receive FIFO. Firmware should take appropriate action. Cleared when read. Additional writes to the RX FIFO are discarded when a RXOVRR occurs until the overrun condition is cleared. Will generate an RXERR interrupt.
SRXCtl.0	PARITYE	Parity Error – (Read only) 1 = The logic detected a parity error on incoming data from the smart card. Cleared when read. Will generate RXERR interrupt.

Byte Control Register (SByteCtl): 0xFE12 ← 0x2C

This register controls the processing of characters and the detection of the TS byte. When receiving, a Break is asserted at 10.5 ETU after the beginning of the start bit. Break from the card is sampled at 11 ETU.

Table 96: The SByteCtl Register

MSB LSB

–	DETTS	DIRTS	BRKDUR.1	BRKDUR.0	–	–	–

Bit	Symbol	Function
SByteCtl.7	–	
SByteCtl.6	DETTS	Detect TS Byte – 1 = Next Byte is TS, 0 = Next byte is not TS. When set, the hardware will treat the next character received as the TS and determine if direct or indirect convention is being used. Direct convention is the default used if firmware does not set this bit prior to transmission of TS by the smart card to the firmware. The hardware will check parity and generate a break as defined by the DISPAR and BRKGEN bits in the parity control register. This bit is cleared by hardware after TS is received. TS is decoded before being stored in the receive FIFO.
SByteCtl.5	DIRTS	Direct Mode TS Select – 1 = direct mode, 0 = indirect mode. Set/cleared by hardware when TS is processed indicating either direct/indirect mode of operation. When switching between smart cards, the firmware should write the bit appropriately since this register is not unique to an individual smart card (firmware should keep track of this bit).
SByteCtl.4	BRKDUR.1	Break Duration Select – 00 = 1 ETU, 01 = 1.5 ETU, 10 = 2 ETU, 11 = reserved. Determines the length of a Break signal which is generated when detecting a parity error on a character reception in T=0 mode.
SByteCtl.3	BRKDUR.0	
SByteCtl.2	–	
SByteCtl.1	–	
SByteCtl.0	–	

Table 99: Divider Values for the ETU Clock

	Fi code	0000	0001	0010	0011	0100	0101
Di code	F→ D↓	372	372	558	744	1116	1488
0001	1	744	744	1116	1488	2232	2976
0010	2	372	372	558	744	1116	1488
0011	4	186	186	279	372	558	744
0100	8	93	93	138	186	279	372
1000	12	62	62	93	124	186	248
0101	16	47	47	70	93	140	186
1001	20	37	37	56	74	112	149
0110	32	23	23	35	47	70	93

	Fi code	0110	1001	1010	1011	1100	1101
Di code	F→ D↓	1860	512	768	1024	1536	2048
0001	1	3720	1024	1536	2048	3072	4096
0010	2	1860	512	768	1024	1536	2048
0011	4	930	256	384	512	768	1024
0100	8	465	128	192	256	384	512
1000	12	310	85	128	171	256	341
0101	16	233	64	96	128	192	256
1001	20	186	51	77	102	154	205
0110	32	116	32	48	64	96	128

CRC MS Value Registers (CRCMsB): 0xFE14 ← 0xFF, (CRCLsB): 0xFE15 ← 0xFF

Table 100: The CRCMsB Register

MSB							LSB
CRC.15	CRC.14	CRC.13	CRC.12	CRC.11	CRC.10	CRC.9	CRC.8

Table 101: The CRCLsB Register

MSB							LSB
CRC.7	CRC.6	CRC.5	CRC.4	CRC.3	CRC.2	CRC.1	CRC.0

The 16-bit CRC value forms the TX CRC word in TX mode (write value) and the RX CRC in RX mode (read value). The initial value of CRC to be used when generating a CRC to be transmitted at the end of a message (after the last TX byte is sent) when enabled in T=1 mode. Should be reloaded at the beginning of every message to be transmitted. When using CRC, both CRC registers should be initialized to FF. When using LRC the CRCLsB Value register should be loaded to 00. When receiving a message, the firmware should load this with the initial value and then read this register to get the final value at the end of the message. These registers need to be reloaded for each new message to be received. When in LRC mode, bits (7:0) are used and bits (15:8) are undefined. During LRC/CRC checking and generation, this register is updated with the current value and can be read to aid in debugging. This information will be transmitted to the smart card using the timing specified by the Guard Time register. When checking CRC/LRC on an incoming message (CRC/LRC is checked against the data and CRC/LRC), the firmware reads the final value after the message has been received and determines if an error occurred (= 0x1D0F (CRC) no error, else error; = 0 (LRC) no error, else error). When a message is received, the CRC/LRC is stored in the FIFO. The polynomial used to generate and check CRC is $x^{16} + x^{12} + x^5 + 1$. When in indirect convention, the CRC is generated prior to the conversion into indirect convention. When in indirect convention, the CRC is checked after the conversion out of indirect convention. For a given message, the CRC generated (and readable from this register) will be the same whether indirect or direct convention is used to transmit the data to the smart card. The CRCLsB / CRCMsB registers will be updated with CRC/LRC whenever bits are being received or transmitted from/to the smart card (even if CRCEN is not set and in mode T1). They are available to the firmware to use if desired.

1.7.18 VDD Fault Detect Function

The 73S1217F contains a circuit to detect a low-voltage condition on the supply voltage V_{DD}. If enabled, it will deactivate the active internal smart card interface when V_{DD} falls below the V_{DD} Fault threshold. The register configures the V_{DD} Fault threshold for the nominal default of 2.3V* or a user selectable threshold. The user's code may load a different value using the FOVRVDDF bit =1 after the power-up cycle has completed

VDDFault Control Register (VDDFCtl): 0xFFD4 ← 0x00

Table 115: The VDDFCtl Register

MSB LSB

–	FOVRVDDF	VDDFLTEN	–	STXDAT.3	VDDFTH.2	VDDFTH.1	VDDFTH.0

Bit	Symbol	Function
VDDFCtl.7	–	
VDDFCtl.6	FOVRVDDF	Setting this bit high will allow the VDDFLT(2:0) bits set in this register to control the VDDFault threshold. When this bit is set low, the VDDFault threshold will be set to the factory default setting of 2.3V*.
VDDFCtl.5	VDDFLTEN	Set = 1 will disable VDD Fault operation.
VDDFCtl.4	–	
VDDFCtl.3	–	
VDDFCtl.2	VDDFTH.2	VDD Fault Threshold. Bit value(2:0) VDDFault voltage 000 2.3 (nominal default) 001 2.4 010 2.5 011 2.6 100 2.7 101 2.8 110 2.9 111 3.0
VDDFCtl.1	VDDFTH.1	
VDDFCtl.0	VDDFTH.0	

* Note: The V_{DD} Fault factory default can be set to any threshold as defined by bits VDDFTH(2:0). The 73S1217F has the capability to burn fuses at the factory to set the factory default to any of these voltages. Contact Teridian for further details.

3.3 Digital IO Characteristics

These requirements pertain to digital I/O pin types with consideration of the specific pin function and configuration. The Row pins have 100KΩ pull-ups.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Voh	Output level, high	Ioh = -2mA	0.8 * V_{DD}		V_{DD}	V
		OFF_REQ pin - I_{OH} = -1mA	V_{DD} - 0.45			V
Vol	Output level, low	Iol = 2mA	0		0.3	V
		OFF_REQ pin – Iol = 2mA			0.45	V
Vih	Input voltage, high	2.7v < VDD <3.6v	1.8		V_{DD} +0.3	V
Vil	Input voltage, low	2.7v < VDD <3.6v	-0.3		0.6	V
		RESET, ON_OFF,PRES pins	-0.3		0.8	V
Ileak	Leakage current	0 < Vin < VDD All output modes disabled, pull-up/downs disabled	-5		5	μA
Ipu	Pull-up current	If provided and enabled, Vout < 0.1v	-5	-3		μA
Ipd	Pull-down current	If provided and enabled, Vout > VDD – 0.1v		3	5	μA

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Iled	LED drive current	Vout = 1.3V, 2.7v < VDD < 3.6v	1.7 3.4 8.5	2 4 10	2.3 4.6 11.5	mA
Iolkrow	Keypad Row output low current	0.0v < Voh < 0.1v when pull-up R is enabled		-40	-100	μA
Iolkcol	Keypad column output high current	0.0v < Voh < 0.1v when col. is pulled low		-1.5	-3	mA

3.6 USB Interface Requirements

Parameter		Condition	Min	Typ.	Max	Unit
Receiver Parameters						
Differential input sensitivity	VDI	|(DP)-(DM)|	0.2			V
Differential common mode range	VCM	Includes VDI range	0.8		2.5	V
Single ended receiver threshold	VSE		0.8		2.0	V
Transmitter Levels						
Low Level Output Voltage	VOL	USBCon = 1 (DP pullup enabled)			0.3	V
High Level Output Voltage	VOH	15KΩ resistor to ground	VDD – 0.1V		VDD	V
Output Resistance (1)						
Driver output resistance	ZDRV	Steady state drive[1]	28		44	Ω
PD Pullup Resistor (to VDD)	Zpu	USBCon = 1	1.2	1.5	1.8	kΩ
Transceiver Power Requirements						
Operating supply current(output)	IPSO	Outputs enabled			5	mA
Operating supply current (input)	IPSI	Outputs Hi-Z			1	mA
Supply current in powerdown	IPDN				10	nA
Supply current in suspend.	IPSS				10	nA

[1] External source (series) termination resistors of 24Ω must be included on circuit board.

Symbol	Parameter	Condition	Min	Typ.	Max	Unit
Interface Requirements – Data Signals: I/O, AUX1 and AUX2						
V_{OH}	Output level, high	I_{OH} =0	0.9 * V_{CC}		V_{CC}+0.1	V
		I_{OH} = -40µA	0.75 V_{CC}		V_{CC}+0.1	V
V_{OL}	Output level, low	I_{OL} = 1mA			0.15 *V_{CC}	V
V_{IH}	Input level, high		0.6 * V_{CC}		V_{CC}+0.30	V
V_{IL}	Input level, low		-0.15		0.2 * V_{CC}	V
V_{INACT}	Output voltage when outside of session	I_{OL} = 0			0.1	V
		I_{OL} = 1mA			0.3	V
I_{LEAK}	Input leakage	V_{IH} = V_{CC}			10	µA
I_{IL}	Input current, low	V_{IL} = 0			0.65	mA
I_{IL}	Input current, low	V_{IL} = 0			0.7	mA
I_{SHORTL}	Short circuit output current	For output low, shorted to V_{CC} through 33Ω			15	mA
I_{SHORTH}	Short circuit output current	For output high, shorted to ground through 33Ω			15	mA
t_R, t_F	Output rise time, fall times	For I/O, AUX1, AUX2, C_L = 80pF, 10% to 90%. For I/OUC, AUX1UC, AUX2UC, CL = 50Pf, 10% to 90%.			100	ns
t_{IR}, t_{IF}	Input rise, fall times				1	µs
R_{PU}	Internal pull-up resistor	Output stable for >200ns	8	11	14	kΩ
FD_{MAX}	Maximum data rate				1	MHz
Reset and Clock for Card Interface, RST, CLK						
V_{OH}	Output level, high	I_{OH} = -200µA	0.9 * V_{CC}		V_{CC}	V
V_{OL}	Output level, low	I_{OL} = 200µA	0		0.15 *V_{CC}	V
V_{INACT}	Output voltage when outside of session	I_{OL} = 0			0.1	V
		I_{OL} = 1mA			0.3	V
I_{RST_LIM}	Output current limit, RST				30	mA
I_{CLK_LIM}	Output current limit, CLK				70	mA
t_R, t_F	Output rise time, fall time	C_L = 35pF for CLK, 10% to 90%			8	ns
		C_L = 200pF for RST, 10% to 90%			100	ns
δ	Duty cycle for CLK	C_L = 35pF, F_{CLK} ≤ 20MHz, CLKIN duty cycle is 48% to 52%.	45		55	%

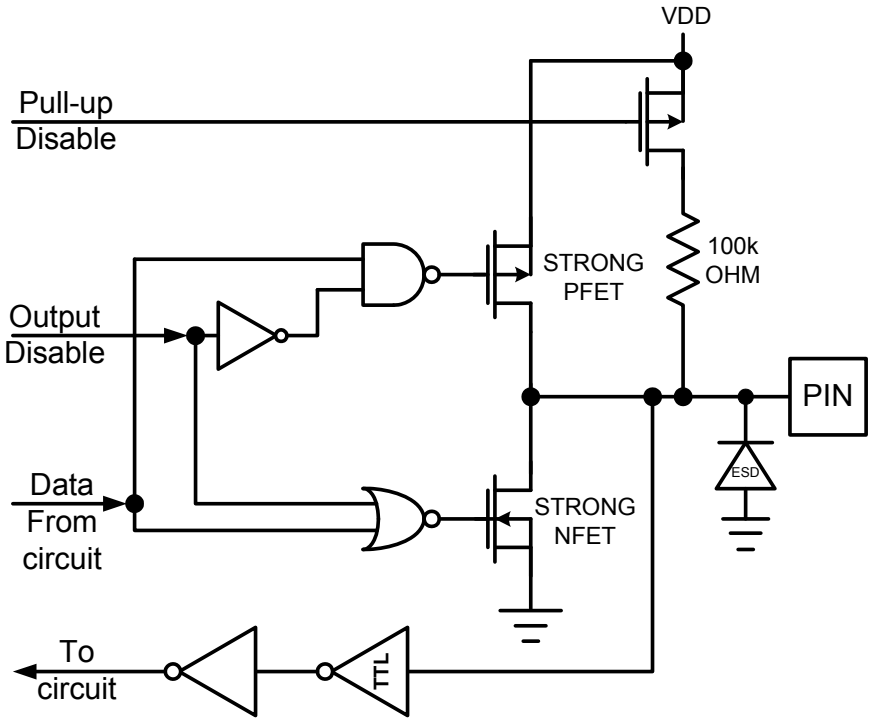

Figure 37: Keypad Row Circuit

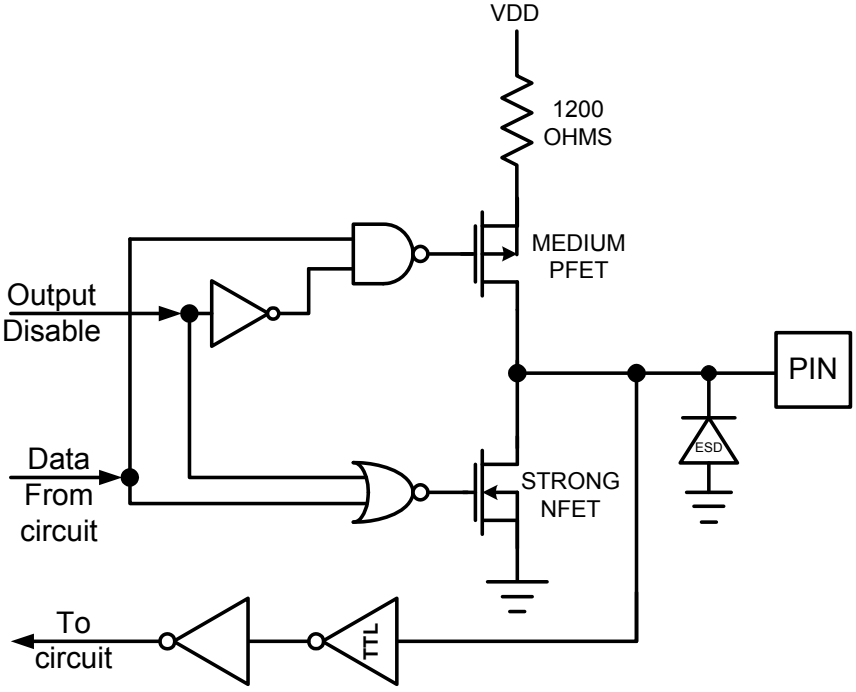

Figure 38: Keypad Column Circuit

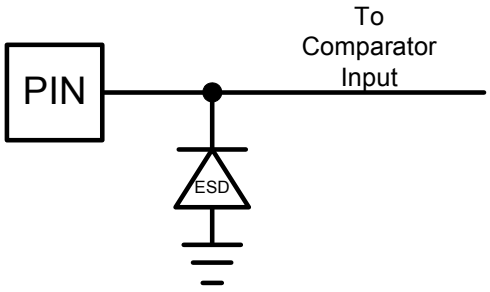

Figure 41: Analog Input Circuit

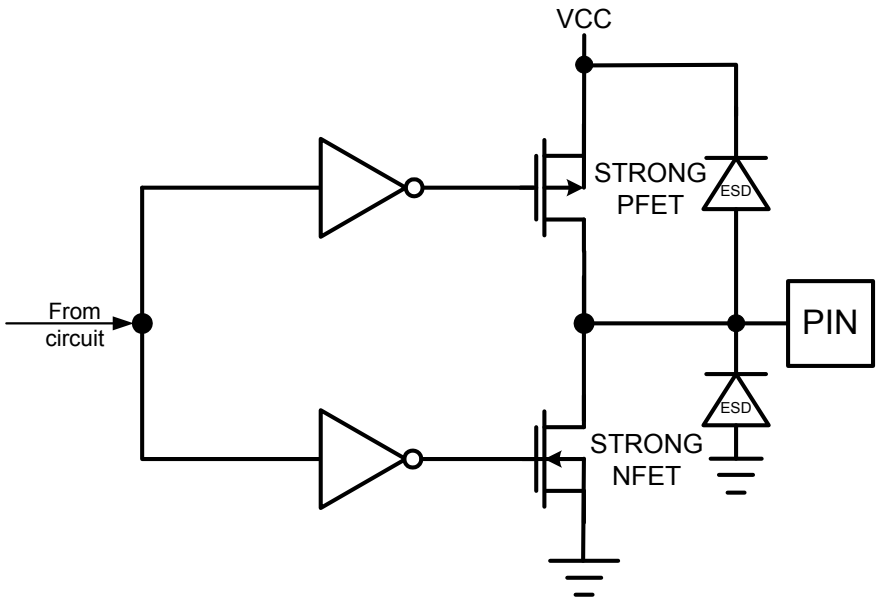

Figure 42: Smart Card Output Circuit